



PATENT

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

In re Application of:

KUO et al.

Group Art Unit: 1765

Serial No.: 09/839,365

Examiner: V. Perez-Ramos

Filed: April 23, 2001

For: METHOD FOR FORMING CONTACT WINDOW

**AMENDMENT**

Assistant Commissioner for Patents  
Washington, D.C. 20231

SEARCHED  
INDEXED  
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SERIALIZED  
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JULY 25 2002  
U.S. PATENT & TRADEMARK OFFICE  
CIVIL

Sir:

This is in response to the Official Action of July 25, 2002, in connection with the above-identified application.

Please amend the above-identified application as follows.

**IN THE CLAIMS:**

Please delete claims 21 and 22 without prejudice or disclaimer.

Please replace claim 1 with the following amended claim 1.

1(Twice Amended). A method for forming a contact window, said method comprise:

forming a plurality of semiconductor structures on a wafer, wherein a plurality of gaps are located between neighboring semiconductor structures;

forming a coating layer over the surface of said wafer, where the thickness of said coating layer is not less than the heights of said semiconductor structures; wherein said semiconductor structures are covered by said coating layer and said gaps are totally filled by said coating layer;